

## AMENDMENTS TO THE CLAIMS

### Listing of Claims

1. (cancelled)
2. (previously presented) A method of making a thickened compound comprising:  
  
preparing a composition consisting essentially of at least one unsaturated oligomer resin, and at least one unsaturated monomer; and  
  
non-reversibly, partially crosslinking said composition a predetermined amount by irradiation to provide a stable, partially crosslinked composition, wherein the viscosity of said composition is increased and further wherein the partially crosslinked composition is capable of being further crosslinked.
3. (previously presented) A method of non-reversibly crosslinking a compound comprising:  
  
preparing a composition comprising an amount of unsaturated oligomer resin, an amount of unsaturated monomer, and an amount of a free radical initiator; and  
  
irradiating the composition with high-energy electrons, wherein a plurality of non-reversible crosslinks are formed, and wherein formation of said crosslinks is dependent upon an absorbed dose and a dose rate of said high-energy electrons and the dose and dose rate are selected to provide a non-reversibly, partially crosslinked compound.

4. (previously presented) A method of preparing a compound which is suitable for use in compression molding operations comprising:

preparing a thermoset mixture consisting essentially of an unsaturated oligomer resin, an unsaturated monomer, and a free radical initiator;

forming a partially crosslinked mixture by selectively irradiating at least a portion of said thermoset mixture to a desired increased viscosity;

placing said partially crosslinked mixture into a mold; and

heating said mold to a temperature sufficient to convert said partially crosslinked mixture to a cured and a molded product.

5-9. (cancelled)

10. (original) The method of claim 2, wherein said composition further comprises materials selected from the group consisting of free radical initiators, polymerization inhibitors, wetting agents, antifoam agents, fillers, fibrous reinforcing materials, pigments, and mold release agents.

11. (previously presented) The method of claim 2, wherein said unsaturated oligomer resin is an unsaturated polyester resin.

12. (original) The method of claim 2, wherein said unsaturated monomer is styrene.

13. (previously presented) The method of claim 10, wherein said free radical initiator is an organic peroxide.

14. (original) The method of claim 2, wherein said composition is non-reversibly crosslinked by selective irradiation from an electron beam of high-energy electrons, with the degree of crosslinking controlled by the electron energy, radiation dose and dose rate.

15-18. (cancelled)

19. (previously presented) A molding compound consisting essentially of:

at least one unsaturated oligomer resin;

at least one unsaturated monomer; and

optionally, at least one free radical initiator;

wherein said compound is non-reversibly crosslinked by irradiation within a predetermined amount to provide a stable, partially crosslinked compound, and wherein the partially crosslinked compound is capable of being further crosslinked.

20. (previously presented) The molding compound of claim 19, wherein the optional free radical initiator is present and comprises an organic peroxide.

21. (new) The molding compound of claim 19, wherein the at least one unsaturated monomer is selected from the group consisting of styrene, methylstyrene,

dimethylstyrene, vinyltoluene, divinylbenzene, dichlorostyrene, methyl acrylate, ethyl acrylate, methyl methacrylate, ethyl methacrylate, diallyl phthalate, vinyl acetate, triallyl cyanurate, acrylonitrile, acrylamide, and mixtures thereof.

22. (new) The molding compound of claim 21, wherein the at least one unsaturated monomer consists of styrene.

23. (new) The molding compound of claim 21, wherein the at least one unsaturated oligomer resin consists of an unsaturated polyester resin.

24. (new) The molding compound of claim 19, wherein said compound is non-reversibly crosslinked by selective irradiation from an electron beam of high-energy electrons.

25. (new) The molding compound of claim 19, comprising at least one fibrous reinforcing material, wherein the amount of crosslinking inhibits flow of said reinforcing materials when the compound is subjected to elevated temperatures.

26. (new) The molding compound of claim 19 additionally containing one or more polymerization inhibitors, one or more wetting agents, one or more antifoam agents, one or more fillers, one or more fibrous reinforcing materials, one or more pigments, one or more mold release agents, or combinations thereof.

27. (new) The method of claim 3, wherein said unsaturated oligomer resin is an unsaturated polyester resin.

28. (new) The method of claim 27, wherein the at least one unsaturated monomer is selected from the group consisting of styrene, methylstyrene, dimethylstyrene, vinyltoluene, divinylbenzene, dichlorostyrene, methyl acrylate, ethyl acrylate, methyl methacrylate, ethyl methacrylate, diallyl phthalate, vinyl acetate, triallyl cyanurate, acrylonitrile, acrylamide, and mixtures thereof.

29. (new) The method of claim 4, wherein said unsaturated oligomer resin is an unsaturated polyester resin.

30. (new) The method of claim 29, wherein the at least one unsaturated monomer is selected from the group consisting of styrene, methylstyrene, dimethylstyrene, vinyltoluene, divinylbenzene, dichlorostyrene, methyl acrylate, ethyl acrylate, methyl methacrylate, ethyl methacrylate, diallyl phthalate, vinyl acetate, triallyl cyanurate, acrylonitrile, acrylamide, and mixtures thereof.